ABSTRACT OF THE DISCLOSURE

A sheet sticking apparatus 10 includes: an openable and closeable case 14 for accommodating a table 11 for supporting a semiconductor wafer W, and forming a decompression chamber C therein; a feeding means 15 for feeding an adhesive sheet S to a position where the adhesive sheet S faces the semiconductor wafer W; and a sandwiching means 29 disposed, in the case 14, in a position relative to the table 11. The sandwiching means 29 sandwiches only an outer periphery portion of the semiconductor wafer W together with the adhesive sheet S by interaction with the table 11 in a state where a single decompression chamber C is formed by closing the case 14. Thereafter, the adhesive sheet S is stuck to the semiconductor wafer W by releasing the reduced pressure in the decompression chamber C.